

**SPECIFICATIONS:**

- ELECTRICAL:**  
 RATED CURRENT: 2A  
 RATED VOLTAGE: 300VDC  
 WITHSTANDING VOLTAGE: 500VAC (rms) FOR 1 MIN  
 INSULATION RESISTANCE: > 1,000 mΩ at 500VDC  
 CONTACT RESISTANCE: 13mOhms MAX  
 DIELECTRIC STRENGTH: 1000VAC FOR 1 MIN  
 OPERATING TEMPERATURE: -55°C TO +105°C

- MATERIALS:**  
 SHELL: 80μ" MIN NICKEL PLATED STEEL  
 BRACKET: 80μ" MIN TIN OVER 50μ" MIN NICKEL PLATED BRASS  
 INSULATOR: NYLON 6T, UL 94V-0, BLACK  
 PROCESS TEMP: 260°C  
 INSULATOR: PATONE #322C, COLOR=Pc99  
 CONTACT: PHOSPHOR BRONZE  
 1μ" MIN GOLD FLASH MATING AREA  
 100μ" MIN TIN PLATED SOLDER AREA

**Storage and Process Instructions:**

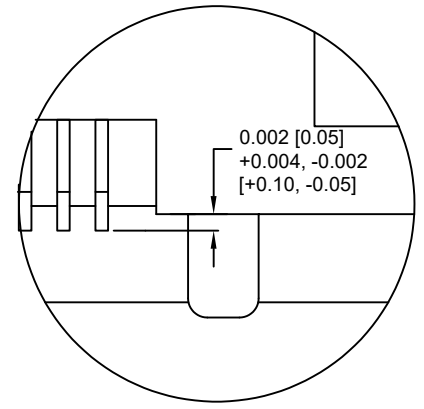
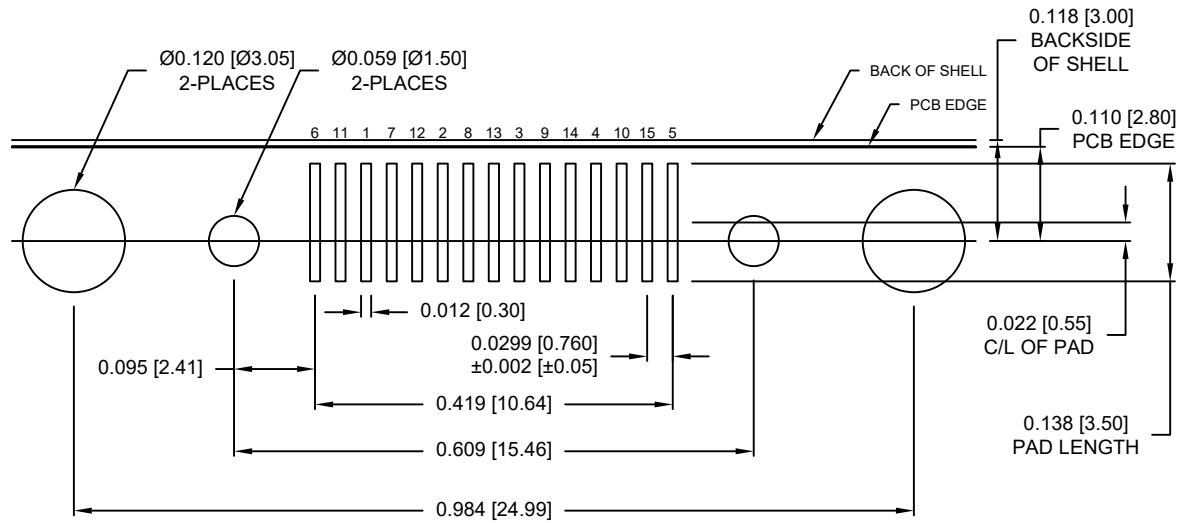
For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

RoHS COMPLIANT

UNITS = inch [mm] DO NOT SCALE FROM DRAWING

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		DATE: 03/27/2009

	SCALE: NTS	SHEET OF 1 2	REV 16
	DWG NO. 200-015-263R001		

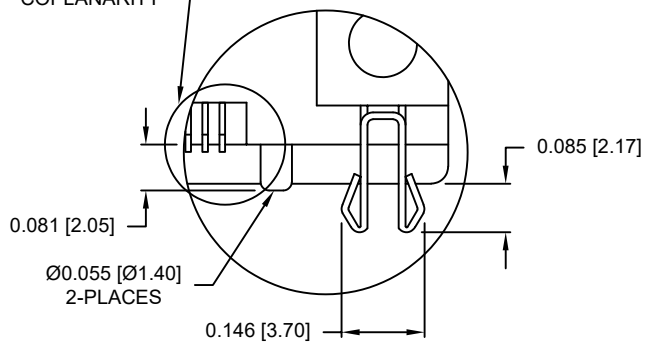


DETAIL "B"  
CONTACT COPLANARITY

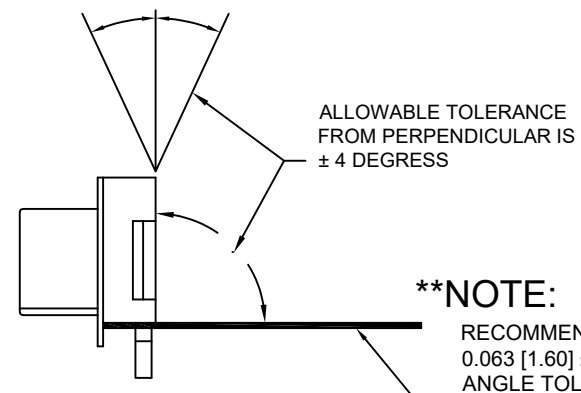
RECOMMENDED PCB LAYOUT

CONTACT ARRANGEMENT  
6 11 1 7 12 2 8 13 3 9 14 4 10 15 5

SEE DETAIL "B"  
FOR CONTACT  
COPLANARITY



DETAIL "A"



**\*\*NOTE:**  
RECOMMENDED PCB THICKNESS IS  
0.063 [1.60] ± 0.002 [0.05] TO MAINTAIN  
ANGLE TOLERANCE

RoHS COMPLIANT

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